喬訊電子工業股份有限公司
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Certificate No:TS 622434 FM 587490

| Type Document | Product Specification | Revised /Edition | O |
|---|---|---|---|
| Date Issued | 2004/01/10 | Data Revised | 2018/11/06 |
| Subject: JS-8001 JS-8001-TJS-8001-TBP JS-6001 JS-7001 Pitch 2.54mm Series Wire to Board Connector | | | Issued By: Engineering Dept. |

*This specification is referred to 2.54mm DIP series wire to board connector.*

*本規格書內容係提供 2.54 mm DIP 系列產品相關參考，*

*其用途為電線端相接於電路板端連接器*

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| REV. (版次) | Revision Record (改版變更原因) | Date(日期) | ECN No |
|---|---|---|---|
| D | 增加PA46 塑料 ‘ 鍍金選項 ‘ 以及10.0 Caution 注意事項 | 2010/12/30 | EC2010-12-013 |
| E | 鹽水噴霧週期以電鍍方式區隔為 8 小時與48 小時 | 2011/05/30 | EC2011-05-085 |
| F | 1.增加溫升測試 2.刪除硫化氫 3.修正(EIA-364) 參考規範 4增列額定電壓 及電流與AWG對照 | 2012/04/18 | EC2012-04-020 |
| G | 增列JS-7001-XX ; JS-7001-XX(L) 使用材質對照 | 2012/08/27 | EC2012-08-015 |
| H | 參照原廠規格修改 Insertion & Withdrawal Force | 2013/02/27 | EC2013-02-027 |
| I | 參照實測平均值 6.1 Insertion Force 修訂為 0.7kg/f Max | 2013/03/22 | EC2013-03-022 |
| J | 1 增訂Wave Peak Soldering In- Process Temperature Profile<br>2.修訂Solder Ability 附註Tin Plated : 95% / Gold Plated : 75%<br>3.修訂 Wire Pullout Force(Axial)規格值 | 2013/12/09 | EC2013-12-009 |
| K | 增訂3.5項Storage of Package以及 3.6 項Floor Life | 2014/01/13 | EC2014-01-013 |
| L | 1.修訂8.9.1 項 Temperature Profile / 2增訂8.7 項Cold耐寒試驗 | 2015/02/24 | EC2015-02-024 |
| M | 增訂8.1 Durability 耐久性 | 2016/6/29 | *EC2016-06-029* |
| N | 增訂8.6項Salt Spray鹽水噴霧 | 2017/10/26 | EC2017-10-026 |
| O | 2.0項新增Matte-Tin Plated | 2018/11/06 | EC2018/11-006 |

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**1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):.**

| Product Name(產品名稱) | | Part Number(零件型號) | Drawing Number(圖面型號) |
|---|---|---|---|
| Crimp Terminal (铆壓端子) | | JS-8001-T | |
| | | JS-8001-PBT | |
| Housing (電線端連接器) | | JS-8001-XX | |
| Wafer (電路板端連接器) | Straight (直立式) | JS-6001-XX | |
| | Right Angle(臥式，導體右側折彎) | JS-7001-XX | |
| | Left Angle (臥式，導體左側折彎) | JS-7001-XX(L) | |

Note: (xx) The number of the circuits

**2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):**

| Part Name(零件名稱) | | | Material(材質) | Surface Finish(表面鍍層) |
|---|---|---|---|---|
| Crimp Terminal | | | Phosphor Bronze | Stamping after tin- plated (先電鍍後衝壓) |
| | | | Brass | |
| Housing | | | Nylon 66 | UL 94V-2 |
| Wafer | Square Pin (方型導體) | JS-7001-XX ; JS-7001-XX(L) | Brass | Tin-Plated or Matte -Plated |
| | | JS-6001-XX | | |
| | | JS-6001-XX(G) | | Gold Flash |
| | Base (膠座) | JS-7001-XX ; JS-7001-XX(L) | PA 66 | UL 94V-2 |
| | | JS-6001-XX | | |
| | | JS-6001-XX(PA) | PA 46 | UL 94V-0 |

**3.0 Characteristic(產品特性):**

| Item(項目) | | Standard(標準規範) | | | | | |
|---|---|---|---|---|---|---|---|
| 3.1 | 額定電流 Rated Current | Conductor Size | AWG | 22# | 24# | 26# | 28# |
| | | | Area($mm^2$) | 0.342 $mm^2$ | 0.220 $mm^2$ | 0.14 $mm^2$ | 0.089 $mm^2$ |
| | | Amp AC/DC | | 3A | 2 A | 1 A | 0.8A |
| 3.2 | 額定電壓 Rated Voltage | 250 V AC/DC | | | | | |
| 3.3 | Ambient Temperature Range 環境與操作溫度範圍 | (操作使用溫度與濕度範圍) Operating Temp.: -25℃~+85℃ ; 85% R.H. Max Including 30℃ Terminal Temperature Rise at rated Current , (包括定額電流內，端子所產生 30℃以下溫昇) | | | | | |
| 3.4 | Applicable Wire 適用電線 | 3.4.1 | (金屬導體型號) Conductor Construction Size: AWG #22~#28 | | | | |
| | | 3.4.2 | (電線絕緣材質外徑) Wire Insulation O.D.: 1.15mm~1.90mm | | | | |

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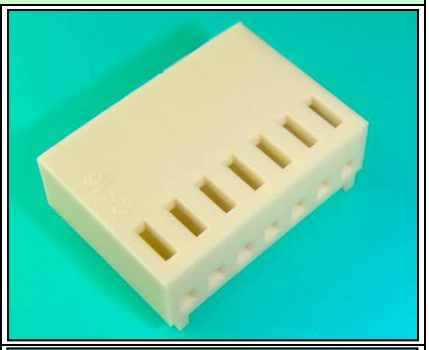
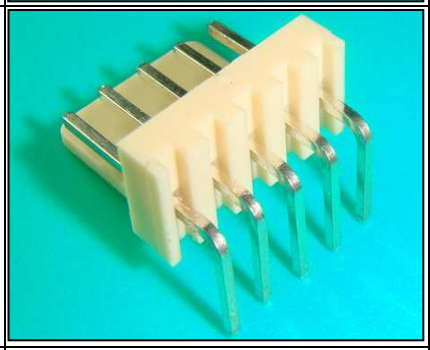
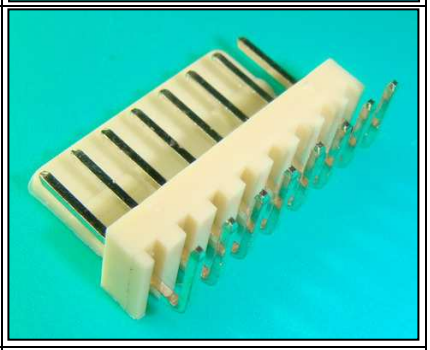
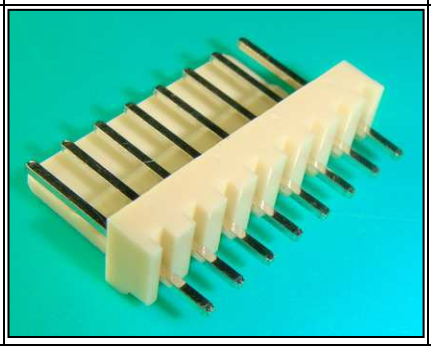
| | | | | |
|---|---|---|---|---|
| 3.5 | Storage of Package 包裝未拆封之保存 | Temperature and Humidity Condition 溫濕度條件 | | Temperature 溫度 : -10℃~+40℃ Percentage Humidity 相對濕度 : 70 % Max |
| | | Term 保存期限 | Housing | 2 Years |
| | | | Crimp Terminal & Wafer | 1 Year |
| 3.6 | Floor Life 拆封後使用期限 | Crimp Terminal & Wafer | | 3 Months |

Note: 適用電路板厚度 Applicable Printed Circuit Board Thickness: 1.6 mm

**4.0 Specimen(樣本圖示) :**

| Part Name / Part Number/ Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示 | | | |
|---|---|---|---|
| Crimp Terminal<br>JS-8001-T<br>JS-8001-PBT |  | Housing<br>JS-8001-XX |  |
| Right Angle<br>Wafer<br>JS-7001-XX |  | Left Angle<br>Wafer<br>JS-7001-XX(L) |  |
| Straight<br>Wafer<br>JS-6001-XX |  | | |

**5.0 Applicable Standards(適用規範):**

**ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.**

電子連接器，所適用之 **ANSI/EIA 364 ; EIA/ECA 364** 測試規範

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**6.0 Mechanical Performance(機械性能):**

| Item(項目) | | Test Condition(測試條件) | | Requirement(規格) |
|---|---|---|---|---|
| 6.1 | Insertion & Withdrawal Force 嵌入力與拔出力 | Insert and withdrawal with connectors at the speed rate of 25 .4 ± 3 mm /minute. 連接器兩端勘合，以每一分鐘 25.4 ± 3mm的速率，作嵌入與拔出往返測試 (EIA/ECA 364-13D) ( Excluding Plastic Detent 不包含膠座卡榫結合力) | | 單一接觸點 Per Contact 嵌入力最大容許值： Insertion Force : 0.7kg/f Max 拔出力最小容許值： Withdrawal Force : 0.06kg/f Min |
| 6.2 | Wire Pullout Force(Axial) 電線脫離端子包覆之拔出力(軸向) | Pull out the cable from contact terminal at the speed rate of 25.4± 3 mm/minute. 對端子所包覆電線，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力 (EIA 364-08B) | AWG#22 size wire | 4.48kgf/Min.(44.0N 牛頓) |
| | | | AWG#24 size wire | 3.57kgf/Min.(35.0N 牛頓) |
| | | | AWG#26 size wire | 2.65kgf/Min.(26N 牛頓) |
| | | | AWG#28 size wire | 1.73kgf/Min.(17N 牛頓) |
| 6.3 | Crimp Terminal Retention Force ( in Housing ) 铆線端子與膠座之間拔出力 | Axial pullout force on the terminal in the housing at the speed rate of 25.4 ± 3 mm per minute. 對於已經存在膠座於當中铆線端子，施以每一分鐘 25 .4± 3 mm 速率之軸向拔出力 (EIA/ 364-05 ) | | 單一接觸點 Per Contact 最小容許值 1.8kgf/Min. |
| 6.4 | Square Pin Retention Force ( in Base ) 方型導體與膠座之間保持力 | Axial pullout force on the square pin in the base at the speed rate of 25.4 ± 3 mm per minute. 對於已經存在於膠座當中方型導體，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力 (EIA/ECA 364-29C ) | | 單一接觸點 Per Contact 最小容許值 1.5kgf/Min. |

**7.0 Electrical Performance(電氣性能) :**

| Item(項目) | | Test Condition(測試條件) | Requirement(規格) |
|---|---|---|---|
| 7.1 | (Low –Signal Level) Contact Resistance (低階信號) 接觸阻抗 | A maximum voltage of 20mV and a maximum current of 100mA are applied to the mate connector. 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 100mA (EIA/ECA 364-23C) ( Does not include wire resistance 不包含電線阻抗 ) | Contact Resistance: 20 milliohms Max. 最大容許值. 20 毫歐姆 |

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| Item(項目) | | Test Condition(測試條件) | Requirement(規格) |
|---|---|---|---|
| 7.2 | Insulation Resistance 絕緣阻抗 | Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C) | Insulation Resistance: Initial 1000 megohms Min 最初容許值. 1000 兆歐姆 |
| 7.3 | Withstanding Voltage 耐電壓 | Apply 1000V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the mate connectors. 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 1000V A/C(實效值) 時間 1 分鐘, 且漏電流必須小於 0.5mA(毫安培) (EIA 364-20C) | No breakdown or flash over. 無損毀或者產生火花 |

**8.0 Environmental Performance(環境性能) :**

| Item(項目) | | Test Condition(測試條件) | Requirement(規格) |
|---|---|---|---|
| 8.1 | Durability 耐久性 | Mate Connectors up 25 Cycles at a Maximun rate of 10 cycles Per minute prior to environmental test 以組合狀態下連接器且未經環境測試，依每分鐘內進行10次嵌入與拔出之最大速率，連續25次嵌入與拔出往返測試 (EIA/ECA 364-09C ) | (After the test) Contact resistance : 40 milliohms Max 經耐久性試驗後接觸阻抗：最大容許值 40 毫歐姆 |
| 8.2 | Temperature Rise (Via Current Cycling) 溫度上昇 (經由電流循環操作) | Mate connector . measure the temperature rise of contact when the maximum rated current is passed 以組合狀態下連接器，通過最大容許電流 量測其導體溫度上昇值 (EIA 364-70B Conditions 1 . Method 1) | Mate connectors Temperature Rise: ＋30℃/Max. 組合狀態下之連接器溫度上昇最大容許值＋30℃ |

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| Item(項目) | | Test Condition(測試條件) | Requirement(規格) |
|---|---|---|---|
| 8.3 | Humidity (Steady State) 恆溫恆濕 | A mated connector shall be placed in a humidity chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.<br>(EIA 364-31B Conditions II. Method A)<br>以組合狀態下連接器放置於恆定溫度與濕度的空間, 依照隨附如下規格要求, 進行恆溫恆濕試驗, 經試驗過後將樣品置於室溫 1~2 小時,再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。<br>Temperature(溫度) : 40±2℃.<br>Relative Humidity(相對濕度) : 90%~95% (RH).<br>Period(週期) : 96 hours continuously. (持續 96 小時) | (After the test)<br>Contact Resistance:<br>40 milliohms Max.<br>經恆溫恆濕試驗後接觸阻抗<br>最大容許值. 40 毫歐姆<br>(After the test)<br>Insulation Resistance :<br>500 Megohms Min.<br>經恆溫恆濕試驗後絕緣阻抗<br>最小容許值. 500 兆歐姆<br>經恆溫恆濕試驗後測耐電壓<br>(After the test)<br>Withstanding Voltage:<br>1000V A/C for 1 minute |
| 8.4 | Thermal Shock 冷熱衝擊 | A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.<br>以組合狀態下連接器作為試驗樣品, 依照隨附如下規格要求, 進行冷熱衝擊試驗 , 經試驗過後將樣品置於室溫 1~2 小時, 再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。<br>(EIA/ECA 364-32D Conditions I . Method A)<br>One Cycle Consists Of:<br>-55℃+0/-3℃ for 30 minutes. → Room Temp. 5 minutes<br>85℃+3/-0℃ for 30 minutes. → Room Temp. 5 minutes<br>Total Cycles: 5 Cycles.<br>以-55℃+0/-3℃溫度持續 30 分鐘 , 經室溫 5 分鐘 , 而後再以 85℃+3/-0℃溫度持續 30 分鐘 , 再經室溫 5 分鐘 , 構成一次冷熱循環 , 總計循環次數 5 次。 | Same as paragraph 8.3<br>同 8.3 章節 |

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| Item(項目) | | Test Condition(測試條件) | Requirement(規格) |
|---|---|---|---|
| 8.5 | Thermal Aging 高溫老化試驗 | A mated connector shall be placed in a heat oven of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於加熱烤箱當中，依照隨附如下規格要求，進行高溫老化試驗，經試驗過後將樣品置於室溫 1~2 小時,再量測其接觸阻抗。<br>(EIA 364-17B Conditions 3 . Method A )<br>Temperature(溫度) : 85±2℃.<br>Period(週期): 96 hours continuously . (持續 96 小時) | Initial Contact Resistance :<br>20 milliohms Max.<br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance :<br>40 milliohms Max. .<br>經高溫老化試驗後接觸阻抗<br>最大容許值. 40 毫歐姆 |
| 8.6 | Salt Spray 鹽水噴霧 | A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行鹽水噴霧試驗 ，試驗過後將樣品用清水沖洗並經過自然風乾，而後量測其接觸阻抗。<br>Density(鹽水密度): 5 % in weight. Temperature(溫度): 35±2℃.<br>Period(週期): Terminal or contact (Stamping after tin plated for 8 hours ) ; Terminal or contact (Stamping before tin plated for 48 hours) 端子或導體(先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時) (EIA 364-26B Conditions B)<br>Salt spray test only define the plating area,without plating area (as copper cross section) will not be defined. 鹽水噴霧測試只判定電鍍區域,無電鍍區域(如折斷面裸銅)則不做判定 | Initial Contact Resistance :<br>20 milliohms Max.<br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance:<br>40 milliohms Max.<br>經鹽水噴霧試驗後接觸阻抗:<br>最大容許值. 40 毫歐姆 |
| 8.7 | Cold 耐寒試驗 (Low Temperature) | A mated connector shall be placed in a cold chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於低溫空間內，依照隨附如下規格要求，進行耐寒試驗，經試驗過後將樣品置於室溫 1~2 小時,再量測其接觸阻抗。<br>(EIA 364-59A Procedure 4)<br>Temperature(溫度) : -25±3℃.<br>Period(週期): 96 hours continuously . (持續 96 小時) | Initial Contact Resistance :<br>20 milliohms Max.<br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance :<br>40 milliohms Max. .<br>經耐寒試驗後接觸阻抗<br>最大容許值. 40 毫歐姆 |

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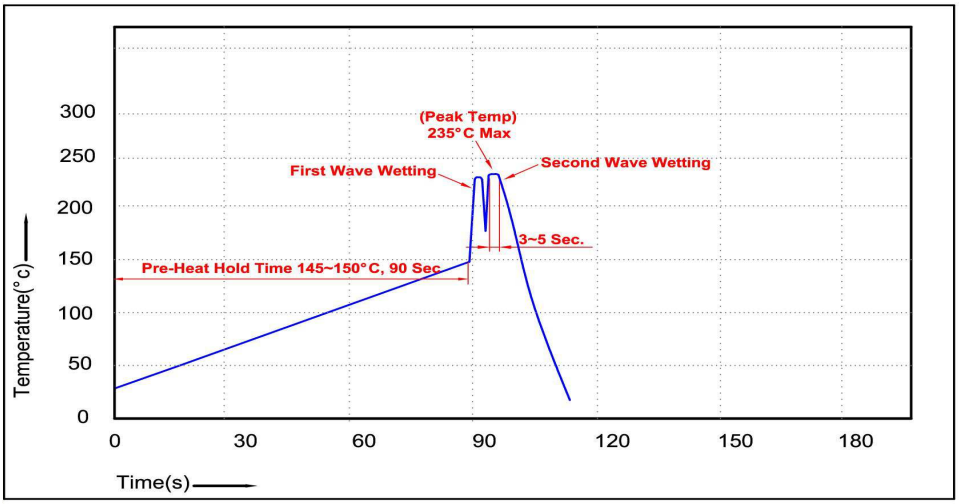
| Date Issued | 2004/01/10 | Data Revised | 2018/11/06 |
| Subject: JS-8001 JS-8001-TJS-8001-TBP JS-6001 JS-7001 Pitch 2.54mm Series Wire to Board Connector | | | Issued By: Engineering Dept. |

| Item(項目) | | Test Condition(測試條件) | Requirement(規格) |
|---|---|---|---|
| 8.8 | Solder Ability 焊錫性 | Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗<br>Solder Temperature (焊錫溫度) : 245 ± 5℃.<br>Immersion Period (沉浸週期) : 3±0.5 Seconds<br>(操作方式) : 零件焊錫位置，距離導體末端 1.5mm<br>Method : 1.5mm from square pin tip (EIA 364-52B) | Solder entirely 95% of immersed area must show no voids or pinholes.<br>焊料覆蓋面積必須達到 95%,<br>而且不能產生氣孔或空隙 |
| 8.9 | Resistance to Soldering Heat 焊錫耐熱性 | Resistance to Wave soldering heat when using PA 66 V2 :<br>使用 Nylon 66V2 塑料，能夠承受波焊耐熱範圍 :<br>Refer to Temperature Profile 請參考 8.9.1.1 溫度曲線圖 | No deformation or damage.<br>不可有變形或損壞 |
| | | Resistance to Wave soldering heat when using PA 46 :<br>使用 PA46 塑料，能夠承受波焊耐熱範圍 :<br>Refer to Temperature Profile 請參考 8.9.1.2 溫度曲線圖<br>(EIA-364-71B) | |
| | | by soldering iron 手工烙鐵焊錫適用溫度範圍 :<br>350 ± 5℃ 3±0.5 Seconds.<br>(操作方式) : 零件焊錫位置，距離導體末端 1.5mm<br>Method : 1.5mm from square pin tip<br>(EIA/ECA 364-56C Procedure 3. Conditions A) | |

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試遵照客戶需求

**8.9.1 Temperature Profile(溫度曲線圖) :**

8.9.1.1 Wave Peak Soldering In- General Process 波焊一般制程



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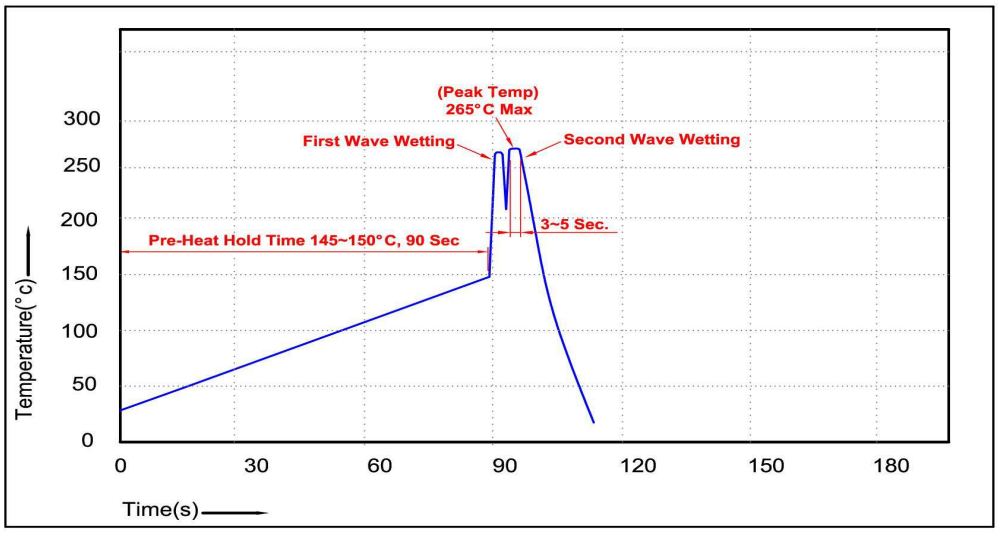
8.9.1.2 **Wave Peak Soldering In-Lead Free Process** 波焊無鉛制程




**9.0Remark(備註)：Any change or revision for the product specification will not be announced in advance.**

**Please contact our sales representative for the latest information.**

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

***Reviewed:*** *Tom Shih* ***Approved:*** *Erin Chou* ***Verified:*** *Eddie*